



SMD Comm X8G HT150C Flex, Ceramic, 6.8 pF, +/-0.1 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	30 mg	
Shelf Life	78 Weeks	
MSL	1	

6.8 pF

1 MHz 1.0Vrms

100 GOhms

Dimensions	
Chip Size	1210
L	3.3mm +/-0.4mm
W	2.6mm +/-0.3mm
Т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm
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Packaging Specifications		

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W	2.6mm +/-0.3mm	Tolerance	+/-0.1 pF
Т	0.78mm +/-0.20mm	Voltage DC	200 VDC
S	1.5mm MIN	Dielectric Withstanding Voltage	500 VDC
В	0.6mm +/-0.25mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
Packaging Specifications		Capacitance Change with	30 ppm/C, 1MegaHz 1.0Vrms
Packaging	T&R, 330mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	., , , ,
Packaging Quantity	10000	Dissipation Factor	0.1% 1 MHz 1.0Vrms
		Dissipation Factor	O.176 TIVINZ I.OVITIS
		Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours

Specifications

Measurement Condition

Insulation Resistance

Capacitance

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